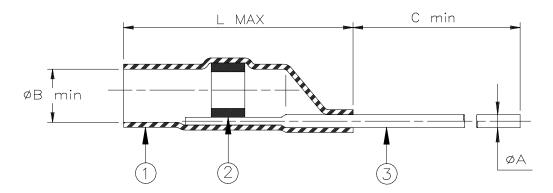
CUSTOMER DRAWING



Product Name		Product D	imensions	Wire Dimensions			
	øΑ	øΒ	С	L	D	S	Size
	max	min	min	max	max	±0.2	AWG
B-801-16	0.68	2.55	10	13.8	2.55	5	20 - 24
B-801-18	0.88	2.55	10	13.2	2.55	5	20 -24
B-801-19	1.08	1.90	8	11.1	1.90	5	22 - 26
B-801-46	0.68	1.90	12	9.2	1.90	4	22 - 26
B-801-48	0.88	1.90	12	9.2	1.90	4	22 - 26

MATERIALS

- 1. INSULATION SLEEVE: Heat-shrinkable, transparent blue, radiation cross-linked modified polyvinylidene fluoride.
- 2. SOLDER PREFORM WITH FLUX:

SOLDER: TYPE Sn62 Pb36 Ag2 per ANSI-J-STD-006.

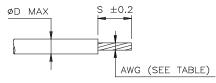
FLUX: TYPE ROL0 per ANSI-J-STD-004.

3. PIN: Cu/Sn-Pb/5b per ASTM B-579-73.

APPLICATION

- 1. These controlled soldering devices are designed for use in attaching a stranded wire, having tin or silver plated conductors, insulations rated for at least 125°C and meeting the dimensional criteria listed, to a printed circuit board having plated-thru holes with a diameter 0.3 to 0.6 larger than the lead diameter (A).
- 2. To install part, strip wire (S). Position sleeve so that the solder preform is over conductor and the pre-installed lead does not overlap wire insulation. Heat, using a suitable heat source and reflector until the solder preform melts and flows to form a fillet between the two wires.
- 3. When installed as above, assembly will meet requirements of Raychem Specification RT-1404 for splices.

For best results, prepare the wire as shown:



Raychem THERMOFIT DEVICES			THERMOFIT	PINPAK* PCB TERMINATOR				
Unless otherwise specified dimensions are in millimeters.			DOCUMENT NO.: B-801-1X, B-801-4X					
TOLERANCES: 0.00 N/A	ANGLI			onnectivity reserves the right to				
0.00 N/A 0.0 N/A 0 N/A	ROUG! MICRO	HNESS IN ON	Users	I this drawing at any time. should evaluate the suitability product for their application.	REV: 4		DATE: 09-Mar-2020	
DRAWN BY: DATE: M. FORONDA 22-Mar-1		ECO: ECO-20-003687		SCALE: NTS		SIZE: A	SHEET: 1 of 1	

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